

Blue are new market stabilizing/positive leaning info. **Orange** are new neutral/negative info.

Device	Company	Production Profile	Comments
NAND	Overall NAND	NAND pricing surged 1H'26; supply constrained through 2027	
	Samsung	Vol.: 286L Ramp: 430L	- Annual licensing renewal required; V10 (430L) ramping - Xi'an upgrade to V8/V9; P4/Hwaseong NAND lines shifting to DRAM
	Kioxia/Sandisk	Vol: 218L Ramp: 332L	- CapEx increase 41% YoY in '26 - BiCS10 332L K2 prod. start 2H'26 AI, cloud & enterprise demand.
	SK Hynix	Vol.: 321L	- Volume production of 321L QLC V9, shifting >50% capacity to support SSD - China export license '26 & likely '27; V10 375L ramp early'27
	Micron	Vol: 276L	- Skipping G10; G11 (>400L, wafer-bonded) ramp 2H'27. Singapore NAND fab remains on track for wafer output 2H'28; ~\$24B investment over 10 years
	YMTC	Vol: 294L	- Wuhan Fab 3 equipment hook-up underway; initial production targeted YE'26, ~100kwsmp at full capacity. Phase 4/5 additional +100k wspm fabs planned
DRAM	Overall DRAM	HBM driving expanded DRAM spend to support AI; 4F ² development in progress	
	Samsung	Vol: 1b nm, Vol.: 1c nm	- Accelerating P5 construction for expected mid-2027 ramp - P4 1c DRAM expanding to 100–120K wspm by 1Q'27, supporting HBM4 ramp
	SK Hynix	Vol: 1b nm, Vol: 1c nm	- '26 CapEx raised to ~\$35B, ~+60% YoY; China export lic. for '26 & likely 2027 - M15X pulled into 1H'26; 75–80K wspm target '26; Yongin F1 cleanroom early'27
	Micron	Vol: 1β nm Ramp: 1γ nm	- FY26 CapEx ~\$27B; FY27 raised to >\$45B (prior ~\$40B) - NY megafab (\$100B) ramp 2030; ID1 first wafers expected mid-FY27 - Japan \$10B adv. DRAM ramp 2H'28; PSMC P5 TW + Boise/SG A&T '27
	ChangXin Mem. Tech. (CXMT)	Vol: 1y Ramp: 1z	- Fab2 (Hefei) ramping; not on entities list but nearing BIS node limit - Shanghai tools 2H'26, E'26 ramp; 320K→420K wspm by '27; NAND line planned
	Other Memory	HBM 1x	- YMTC: new Wuhan fab 50% DRAM for HBM, 2027; LPDDR5 trial prod. E'26 - Nanya: updated 2026 CapEx to >\$1.6B; announced 2027 4x CapEx increase - Winbond: accelerated Kaohsiung ramp of 16nm with tools moving in 2H26
Foundry/Logic	Foundry/Logic	Leading & trailing nodes investment planned. Advanced packaging is capacity limited.	
	≤16nm	TSMC 3nm 2nm GAA	- FY'26 CapEx to ~\$60-64B; indicated expansive spend increase to support AI/HPC - Total US investment \$165B, potential additional \$100B & acquired new site - AZ (Fab1 4nm, 2025; F2 3nm, 2026; F3 2nm, 2027), Japan fab2 (3nm, 2028)
		Intel 4nm 18A / 14A	- CapEx >\$20B (raised), \$23B equity raise; ~\$6B Ireland; Ohio TBD - AZ 18A ramping (yields ahead of plan); 14A risk 2H'27, HVM '28; Terafab 14A lic.
		Samsung	- '26 CapEx +22%; Taylor 2nm trial Sep'26 (pulled in), booked; 20K wspm 2H'27 - Taylor F2 const. E'26, HVM 2030; Yongin pulled in, F1 2029, 6 fabs/2040 (\$230B)
		Terafab	- Ph1 Grimes CapEx. \$16.8B (>\$100B all phases); Austin R&D fab first test chip mid-27; volume targeted 3Q'28 (Musk) but consensus 2030
		Rapidus	- Production goal for 2027 accelerating ramp, \$3-4B CapEx '25 → ~\$8B 2026. - 1.4nm Hokkaido fab const. 2027; METI +\$2.5B equity FY27-29; \$12.7B loans
	≥20nm	GlobalFoundries	- Malta: 2 new 300mm fabs (US-JP, up to \$21B); F1 online 2029, ~900K wpy ea.
		SMIC	- Target increase 5x 7nm/5nm output by 2028, affirming >\$8B CapEx annually
		TSMC	- Japan Fab 23 P2 considering migrating to more advanced nodes (3nm). - Dresden JV fab (target tool move-in 2H26, ramp 2H 2027-end);
		UMC	- '26 CapEx inc. to \$2B, ~\$5B through '28; Tainan P7/8 & SG P4, ramp late'27-28
		SMIC	- Continuing high spending with \$8B+ forecast for 2026, Beijing fab start '2H26
		Powerchip	- Tongluo site acquired by Micron; Technology license sale to Tata (India) - Focus on advanced 3D integration from mature-nodes to support AI
		GlobalFoundries	- Dresden ~\$1.3B total ('25–'28) topped out Oct.'26; ~950K → >1M wpy by E'28
		Other	- US: TI '26 CapEx at high end of \$2-3B, tooling Sherman shells - China: CanSemi +40K, Hua Hong +30K, Wingsky (45K), Zensemi, CR Micro - Japan: Toshiba (P2 '26), slowed/inactive: Renesas; Rohm, Sanken, Sony. - Europe: ST (Crolles on hold); Infineon (Dresden, 2026); India: Tata delay cont.
		TSMC	- \$5-10B (10-15% CapEx) for AI; CoWoS capacity ~2x by E'26 - 2 AZ adv. pkg fabs in \$265B plan; AZ AP prod. 2029, US CoWoS via TW
		Intel	- Consolidating sites (closing Costa Rica); canceled Poland plan (2027).
		GlobalFoundries	- Adding adv. pkg & test to Malta; \$955M CHIPS realloc. to SiPh/SiGe/pkg
		SK Hynix	- Indiana HBM move into 2H'29; \$13B Cheongju site ramp '27
		OSAT	- Starting capacity add for adv. Packaging; CoWoS pkg. bottleneck to persist to '28
Packaging			